

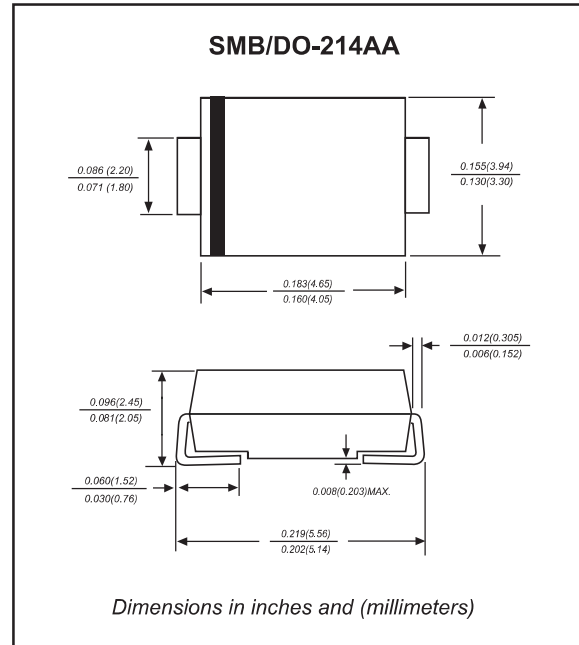
Features

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ For surface mounted applications
- ▶ Low reverse leakage
- ▶ Built-in strain relief, ideal for automated placement
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ▶ Glass passivated chip junction
- ▶ Compliant to RoHS Directive 2011/65/EU

Mechanical data

- ▶ **Case:** JEDEC DO-214AA molded plastic body
- ▶ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity:** Color band denotes cathode end
- ▶ **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I_O			2.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			60	A
Reverse current	$V_R = V_{RRM}$ $T_A = 25^\circ\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM}$ $T_A = 100^\circ\text{C}$				50	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		50		$^\circ\text{C/W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		30		pF
Storage temperature		T_{STG}	-65		+150	$^\circ\text{C}$

Note: 1.P.C.B. mounted with 2.0x2.0"(5.0x5.0cm) copper pad areas

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature $T_{J,}$ ($^\circ\text{C}$)
S2AB	50	35	50	1.10	-55 to +150
S2BB	100	70	100		
S2DB	200	140	200		
S2GB	400	280	400		
S2JB	600	420	600		
S2KB	800	560	800		
S2MB	1000	700	1000		

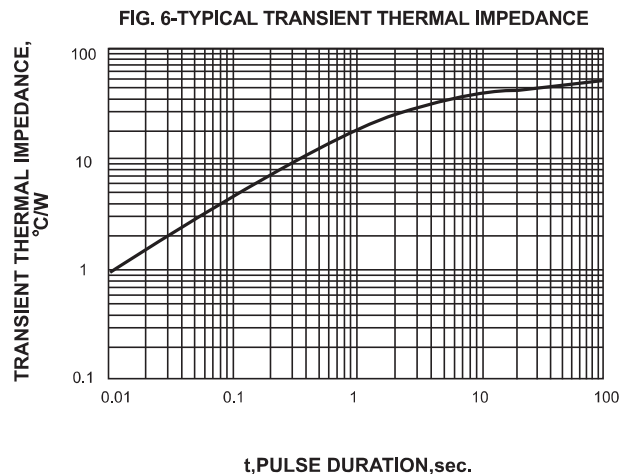
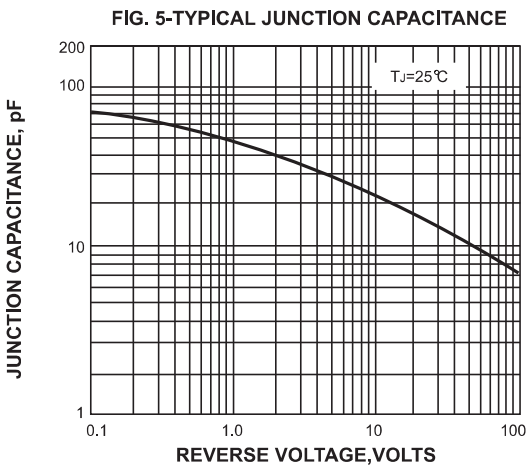
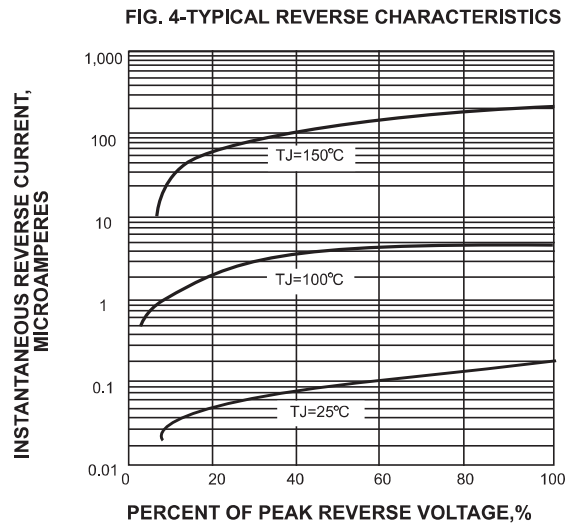
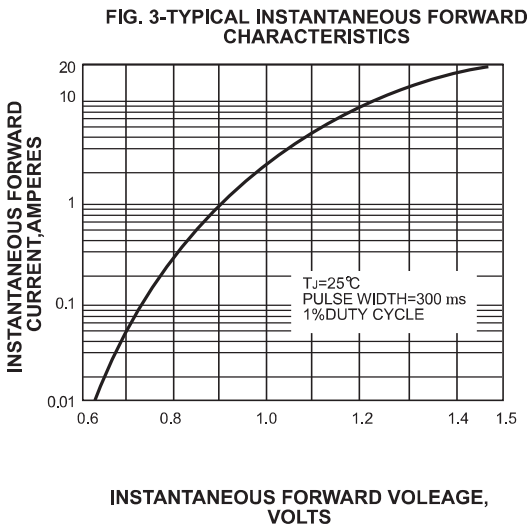
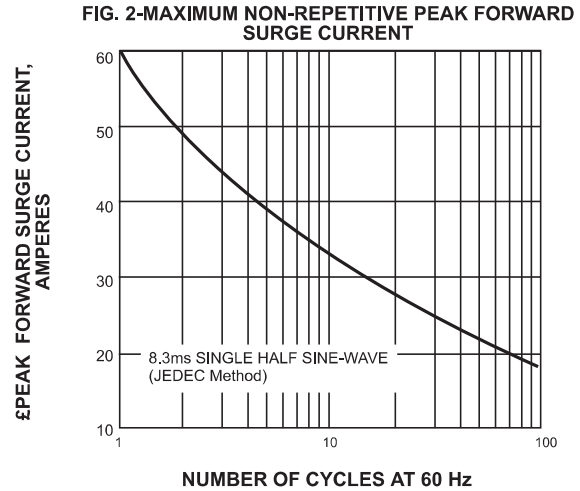
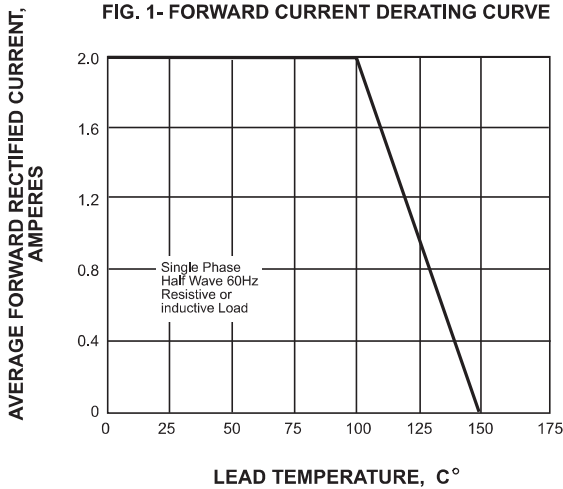
*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=2.0\text{A}$

Rating and characteristic curves



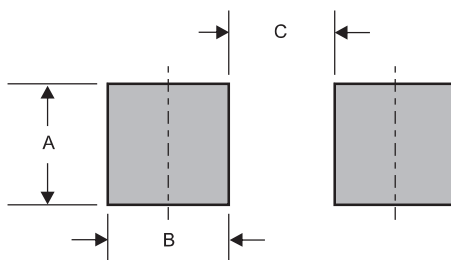
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
S2AB	S2A	
S2BB	S2B	
S2DB	S2D	
S2GB	S2G	
S2JB	S2J	
S2KB	S2K	
S2MB	S2M	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB	0.078 (2.00)	0.059 (1.50)	0.110 (2.80)